



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-11-14
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TSZ1521YST	ASE3*VB4XAAY	A	Z9LA SC	2024-11-14
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	25.60	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy		Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		0

Package designator	Package size	Number of instances	Shape	
DSO	3x3	8	gull wing	
Comment				
Comment	E3 MSOP/TSSOP 8 BODY3.00 PITCH0.65			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 17th Nov 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			true
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			false
Substance	amount in product (mg)	Application	ppm in product

QueryList :Customer		Response
QUERY		Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
QUERY					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
O	O	O	O	O	O

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ASE3*VB4XAY		25.6010		6000141.0	1000042.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.668	mg	supplier	die	Silicon(Si)	7440-21-3		0.629	mg	941617	24570
				supplier	metallisation	Aluminium(AI)	7429-90-5		0.008	mg	11976	313
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	1497	39
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	1497	39
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.003	mg	4491	117
				supplier	passivation	Silicon oxide	7631-86-9		0.015	mg	22455	586
				supplier	polymer coating	polyimide	proprietary		0.011	mg	16467	430
				supplier	alloy	Copper (Cu)	7440-50-8		6.783	mg	969000	264961
Leadframe	M-004 Copper and its alloys	7.000	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.158	mg	22571	6172
				supplier	alloy	Phosphorus (P)	7723-14-0		0.011	mg	1571	430
				supplier	alloy	Zinc(Zn)	7440-66-6		0.007	mg	1000	273
				supplier	alloy	Silver(Ag)	7440-22-4		0.042	mg	6000	1641
				supplier	glue	Silver	7440-22-4		0.243	mg	810000	9492
Die attach	M-011 Other inorganic materials	0.300	mg	supplier	glue	Acrylic resin	Proprietary		0.023	mg	75000	879
				supplier	glue	Polybutadiene derivative	Proprietary		0.009	mg	30000	352
				supplier	glue	Acrylate	Proprietary		0.012	mg	40000	469
				supplier	glue	Epoxy resin	Proprietary		0.006	mg	20000	234
				supplier	glue	Butadiene copolymer	Proprietary		0.003	mg	10000	117
				supplier	glue	Additive	Proprietary		0.003	mg	10000	117
				supplier	glue	Peroxide	Proprietary		0.002	mg	5000	59
				supplier	wire	Cu	7440-50-8		0.940	mg	970000	36716
Bonding wires 2	M-004 Copper and its alloys	0.969	mg	supplier	wire	Cu	7440-50-8		0.940	mg	970000	36716
0				supplier	wire	Pd	7440-05-3		0.029	mg	30000	1136
Encapsulation	M-011 Other inorganic materials	14.663	mg	supplier	mold compound	Epoxy Resin 1	Proprietary		0.331	mg	22587	12938
				supplier	mold compound	Epoxy Resin 2	Proprietary		0.331	mg	22587	12938
				supplier	mold compound	Epoxy Resin 3	Proprietary		0.331	mg	22587	12938
				supplier	mold compound	Phenolic Resin	Proprietary		0.414	mg	28234	16172
				supplier	mold compound	Catalyst	Proprietary		0.083	mg	5647	3234
				supplier	mold compound	Carbon black	1333-86-4		0.033	mg	2259	1294
				supplier	mold compound	Amorphous silica1	60676-86-0		11.615	mg	805748	461511
				supplier	mold compound	Amorphous silica2	7631-86-9		1.325	mg	90350	51750
Connections coating	Solder	2.000	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		2.000	mg	1000000	78125